

ABSTRACT OF THE DISCLOSURE

A method and system for trimming a feature on a substrate is described. During a chemical treatment of the substrate, the substrate is exposed to a reactive gaseous chemistry, such as HF/NH₃, under controlled conditions including surface temperature and gas pressure. An inert gas can, for example, also be introduced with the reactant gaseous chemistry. The period of time during which the substrate is exposed to the reactive gaseous chemistry is selected in order to affect a target trim amount during the trimming of the feature.